**Features:**

- n Isolated mounting base 2500V~
- n Solder joint technology with
Increased power cycling capability
- n Space and weight saving

Typical Applications

- n Inverter
- n Inductive heating
- n Chopper

V_{RSM}	V_{RRM}	Type & Outline
900V	800V	MDS200-08-411H5
1100V	1000V	MDS200-10-411H5
1300V	1200V	MDS200-12-411H5
1500V	1400V	MDS200-14-411H5
1700V	1600V	MDS200-16-411H5
1900V	1800V	MDS200-18-411H5

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_j(^{\circ}C)$	VALUE			UNIT
				Min	Type	Max	
I_O	DC output current	Three-phase full wave rectifying circuit, $T_C=100^{\circ}C$	150			200	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			12	mA
I_{FSM}	Surge forward current	10ms half sine wave	150			1.5	kA
I^2t	I^2t for fusing coordination	$V_R=0$				11.25	$A^2s \cdot 10^3$
V_{FO}	Threshold voltage		150			0.75	V
r_F	Forward slope resistance					2.0	mW
V_{FM}	Peak forward voltage	$I_{FM}=200A$	25			1.50	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled, per total				0.10	$^{\circ}C/W$
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled, per total				0.07	$^{\circ}C/W$
V_{iso}	Isolation voltage	50Hz,R.M.S,t=1min, $I_{iso}:1mA(max)$		2500			V
F_m	Terminal connection torque(M6)			4.5		6.0	N·m
	Mounting torque(M5)			2.5		4.0	N·m
T_{vj}	Junction temperature			-40		150	$^{\circ}C$
T_{stg}	Stored temperature			-40		125	$^{\circ}C$
W_t	Weight				330		g
Outline	411H5						

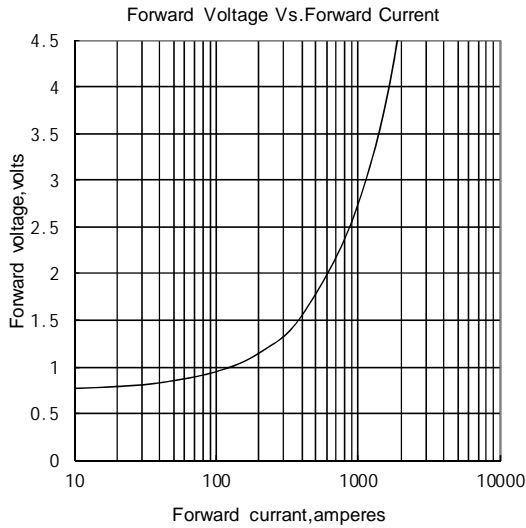


Fig.1

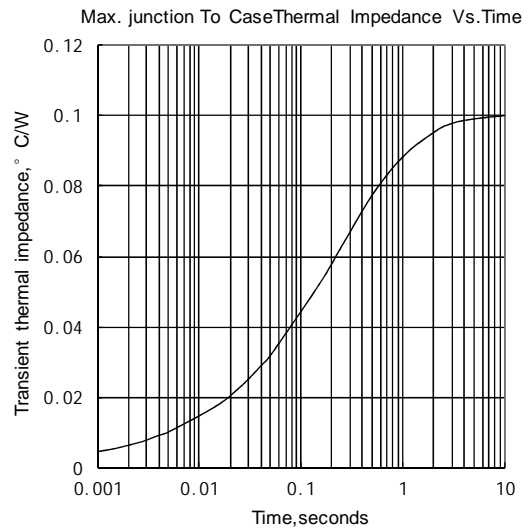


Fig.2

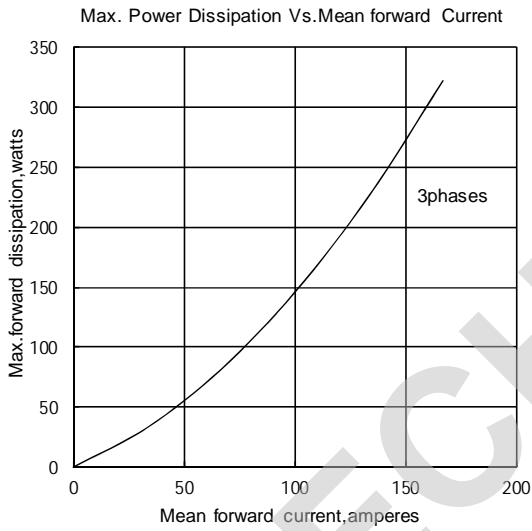


Fig.3

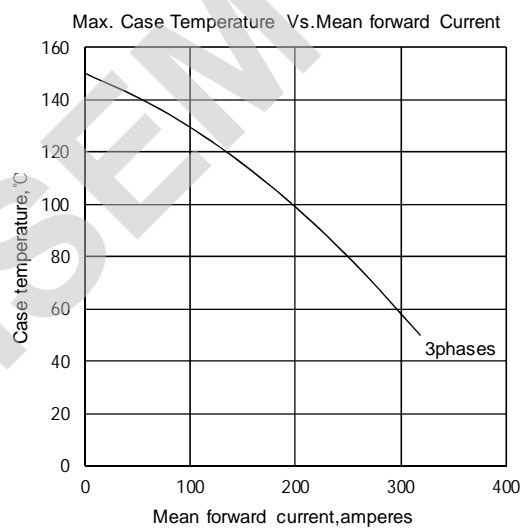


Fig.4

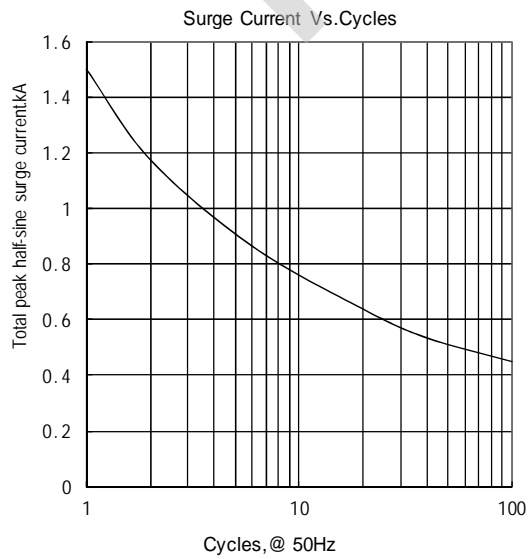


Fig.5

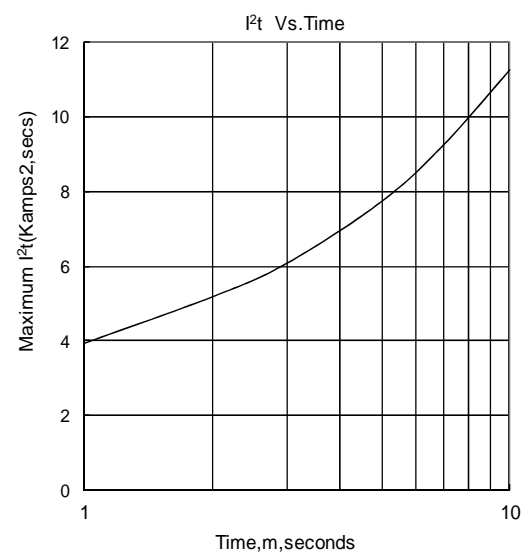
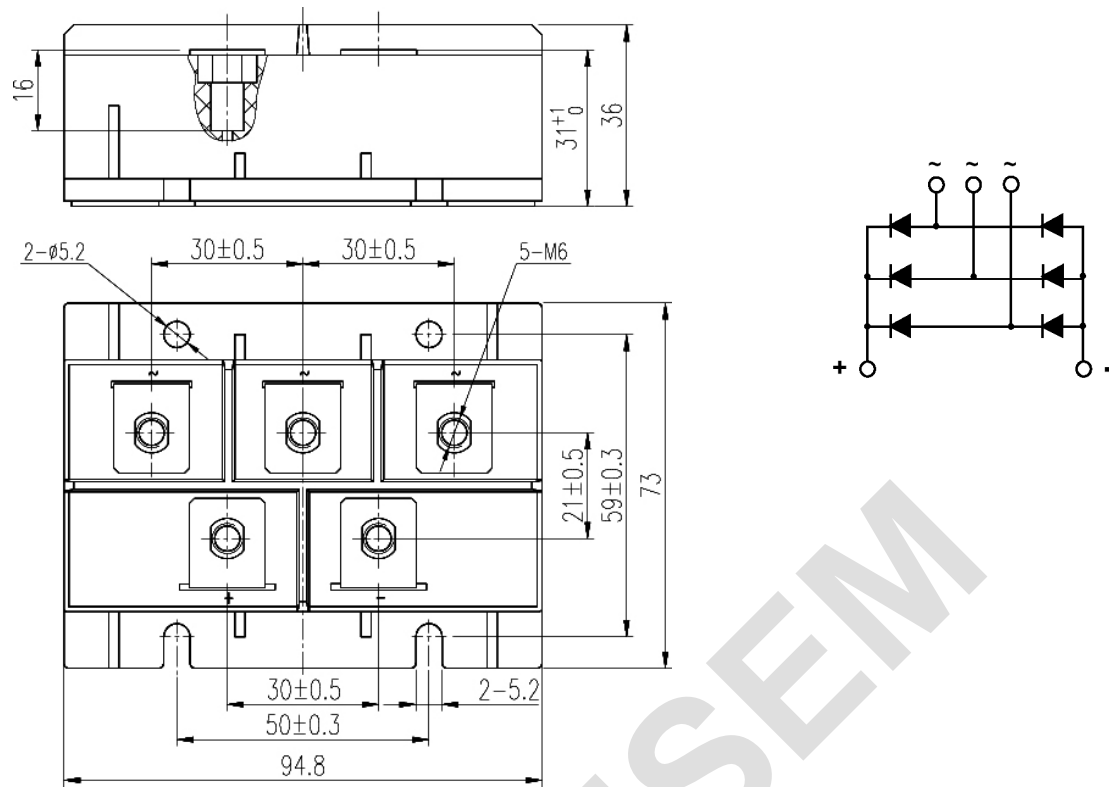


Fig.6

Outline:



Unmarked dimensional tolerance: $\pm 0.5\text{mm}$

TECHSEM reserves the right to change specifications without notice.